mixing a bismaleimide compound and a monomeric furan compound, said monomeric furan compound containing an oxirane group, at an elevated temperature of greater than approximately 90°C to form a homogeneous solution;

mixing a curative at said elevated temperature to form a second homogeneous mixture; and

cooling said second homogeneous mixture to a temperature less than approximately 70°C to simultaneously initiate a Diels-Alder reaction between said furan and said bismaleimide and a epoxy curing reaction between said curative and said oxirane group, thereby forming a thermally-removable adhesive.

- 2. The method of claim 1 wherein the curative is selected from the group consisting of amine curatives, anhydrides, carboxylic acids, and alcohols.
- 3. The method of claim 1 wherein the curative is selected from the group consisting of chlorendic, dodecenylsuccinic anhydride, nadic methyl anhydride, pyromellitic dianhydride, maleic anhydride, 3-3'-dimethylmethylenedi(cyclohexylamine), polyoxypropylenediamine, and nonylphenol.
- 4. The method of claim 1 wherein the monomeric furan is furfuryl glycidyl ether.

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- 5. The method of claim 1 wherein the bismaleimide compound is selected from 1,1'-(methylenedi-4,1-phenylene)-bismaleimide, N,N'-(4-methyl-1,3-phenylene)-bismaleimide, N,N'-m-phenylene-bismaleimide, and ((C₄H₂O₂N)C₆H₄)₂(OSi(CH₃)₂)₄O.
- 6. The method of claim 1 wherein the second homogeneous mixture is formed within less than approximately 20 minutes.

The method of claim 1 wherein heating said thermally-removable adhesive to a temperature greater than approximately 100°C initiates melting of the adhesive.

6. A method of adhering two pieces together, comprising:

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mixing a bismaleimide compound and a monomeric furan compound, said monomeric furan compound containing an oxirane group, at an elevated temperature of greater than approximately 90°C to form a homogeneous solution;

mixing a curative at said elevated temperature to form a second homogeneous mixture;

cooling said second homogeneous mixture to a temperature less than approximately 70°C to form a thermally-removable adhesive;

contacting said thermally-removable adhesive to the surface of a first piece;

heating to a temperature greater than approximately 90°C; contacting the surface of a second piece to the thermally-removable adhesive to form a two-piece system; and

curing said two-piece system by cooling to less than approximately 70°C to adhere the first piece to the second piece.

- 9. The method of claim 8 wherein said first piece is separated from said second piece by heating to a temperature greater than approximately 100°C.
- 10. The method of claim 8 wherein the step of heating to a temperature greater than approximately 90°C is performed after the surface of the first piece and the surface of the second piece have been contacted to the thermallyremovable adhesive.
- 11. The method of claim 8 wherein the bismaleimide compound is selected from 1,1'-(methylenedi-4,1-phenylene)-bismaleimide, N,N'-(4-methyl-1,3-phenylene)-bismaleimide, N,N'-m-phenylene-bismaleimide, and ((C₄H₂O₂N)C₆H₄)₂(OSi(CH₃)₂)₄O.
- 12. The method of claim 8 wherein the curative is selected from the group consisting of amine curatives, anhydrides, carboxylic acids, and alcohols.
- 13. The method of claim 8 wherein the curative is selected from the group consisting of chlorendic, dodecenylsuccinic anhydride, nadic methyl anhydride, pyromellitic dianhydride, maleic anhydride, 3-3'-dimethylmethylenedi(cyclohexylamine), polyoxypropylenediamine, and nonylphenol.
- 14. A method to form a conformal coating solution, comprising comprising the steps of:

mixing a bismaleimide compound and a monomeric furan compound, said monomeric furan compound containing an oxirane group, at an elevated temperature of greater than approximately 90°C to form a homogeneous

solution;

mixing a curative at said elevated temperature to form a second homogeneous mixture;

applying said diluted homogeneous mixture to a surface at a temperature less than approximately 70°C to simultaneously cure and evaporate at least a portion of said solvent to form a thermally-removable conformal coating.

- 15. The method of claim 14 wherein said solvent is a polar solvent.
- 16. The method of claim 14 wherein the bismaleimide compound is selected from 1,1'-(methylenedi-4,1-phenylene)-bismaleimide, N,N'-(4-methyl-1,3-phenylene)-bismaleimide, N,N'-m-phenylene-bismaleimide, and ((C₄H₂O₂N)C₆H₄)₂(OSi(CH₃)₂)₄O.
- 17. The method of claim 14 wherein the curative is selected from the group consisting of amine curatives, anhydrides, carboxylic acids, and alcohols.
- 18. The method of claim 14 wherein the curative is selected from the group consisting of chlorendic, dodecenylsuccinic anhydride, nadic methyl anhydride, pyromellitic dianhydride, maleic anhydride, 3-3'-dimethylmethylenedi(cyclohexylamine), polyoxypropylenediamine, and nonylphenol.
- 19. The method of claim 14 wherein the surface is a surface of a printed wire board.